• Project Title:

• Project team members, their academic information/affiliation and contact details (UG/PG/Ph.D. students and faculty).

• Role of each member in the project:

• Source of funding for the project:

• Introduction and motivation (maximum 300 words):

• Category
  o Post Layout Simulation
  o Fabricated silicon chip with measurement results

• Domain (up to 3 choices)
  o Digital
  o Analog
  o Mixed Signal
  o RF
  o MMIC
  o Memory

• Block diagram (1 page)
  o Complete block diagram of the test chip including main modules, on-chip input/output buffers, test blocks (if any).

• Schematic of main modules (maximum 2 pages)
• Technology and layout details, chip micrograph (if fabricated)
• Post layout simulations and measurement results (maximum 2 pages)

• Table of comparison with the literature and main features as compared with the prior art (1 page)
• Period of the project (The proposed design and layout with fabrication and test (if applicable))
  o Beginning date
  o End date
  o Milestones (6-monthly or quarterly)

• List of publications/patent application details based on the proposed idea.